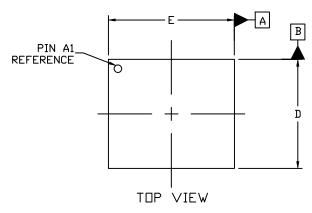
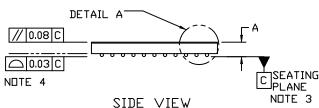
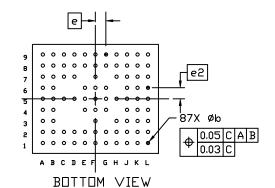




DATE 19 MAY 2023

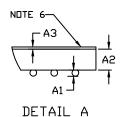






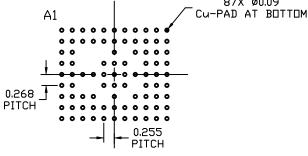
NOTES:

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009
- CONTROLLING DIMENSION: MILLIMETERS
 DATUM C, THE SEATING PLANE, IS DEFINED BY
 THE SPERICAL CROWNS OF THE CONTACT BALLS.
 COPLANARITY APPLIES TO THE SPHERICAL CROWNS
- DF THE CONTACT BALLS.
 DIMENSION 6 IS MEASURED AT THE MAXIMUM
 CONTACT BALL DIAMETER PARALLEL TO DATUM C.
 BACKSIDE COATING.



	MILLIMETERS			
DIM	MIN.	N□M.	MAX.	
Α	0.329	0.354	0.379	
A1	0.060	0.075	0.090	
A2	0.241	0.254	0.267	
A3	0.025 REF			
b	0.087	0.102	0.117	
D	2.593	2.643	2.693	
E	3.003	3.053	3,103	
е	0.255 BSC			
e2	0.268 BSC			

87X Ø0.09



RECOMMENDED MOUNTING FOOTPRINT* (NSMD PAD TYPE)

GENERIC MARKING DIAGRAM*

XXXXXXX **AWLYYWW**

XXXX = Specific Device Code

= Assembly Location WL = Wafer Lot

ΥY = Year WW = Work Week *This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "=", may or may not be present. Some products may not follow the Generic Marking.

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DESCRIPTION:	WLCSP87 2.643x3.053x0.3	54	PAGE 1 OF 1	

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